

## X32系列/X32 Series

**CHX32SB-xx.xxxMxxxBx-NT**

(料号参考下页选型指南)

**Pb Free** **RoHS Compliant**  
2002/95/EC



### ※ 应用及特点 Application & Features

- 电脑、网卡、通讯 Computer, Modem, Communications
- 蓝牙、无线 Bluetooth, Wireless
- 自动控制设备及其它 Automotive Equipment at Other
- 金属封装尺寸: 3.2×2.5×0.8mm Metal Package

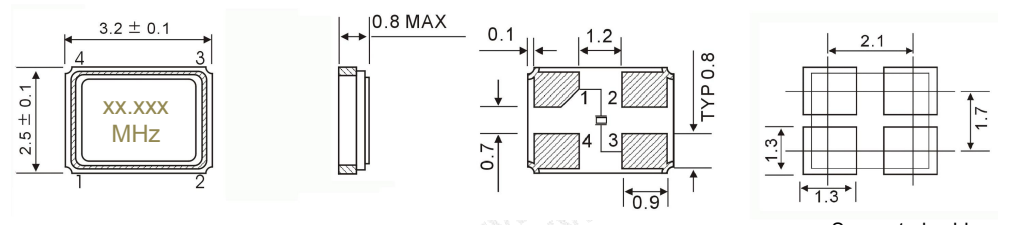
### ※ 电气参数 Electrical Specification

项目 Item	参数 Parameter
频率范围 Frequency Range	12.000 to 50.000MHz
调整频差 Frequency Tolerance) ( $\Delta F$ )(at25°C)	$\pm 10$ to $\pm 50$ ppm
温度频差 Frequency Drift)	$\pm 10$ to $\pm 50$ ppm
工作温度 Operating Temperature Range	-20 to 70 / -40 to 85 °C
储存温度 Storage Temperature Range	-40 to 85 °C
负载电容 Load Capacitance , (CL)	Suggested by customer(6-50PF/或串联)
激励功率 Drive Level)	10 $\mu$ W to 100 $\mu$ W
静态电容 Shunt Capacitance ,(C0)	7.0pF Max
老化率 Aging at 25 °C	$\pm 5$ ppm/year Max
绝缘阻抗 Insulation Resistance (Rs)	500M $\Omega$ Min at100Vdc

### ※ 等效电阻和振荡模式 Equivalent Series Resistance (ESR) and Mode of Oscillation

频率范围 Frequency Range (MHz)	等效阻抗 ESR( $\Omega$ )	振荡模式 Mode of Oscillation
12.000 - 20.000 MHz	100 Max	基频 AT Fund
20.000 - 30.000 MHz	80 Max	基频 AT Fund
30.000 - 40.000 MHz	60 Max	基频 AT Fund
40.000 - 50.000 MHz	40 Max	基频 AT Fund

### ※ 外形尺寸及印字 Mechanical Dimensions and Marking

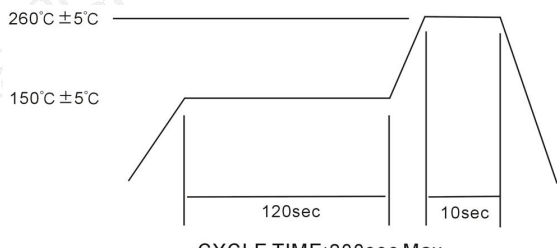


UNIT(单位):mm(毫米)

#1	输入
#3	输出
#2、4	接地

Suggested solder pad layout 推荐焊盘

## ※ 应用环境标准 Environmental /Mechanical SPEC

项目 Item	参数 Parameter	回流焊条件 Reflow Condition
耐冲击性 Shock Resistance	跌落测试:75cm 高度,跌落三次至硬木板 Drop from Height 75cm to hard wooded board 3 times	 <p>CYCLE TIME:200sec Max.</p>
焊接条件 Solder Condition	引线焊接时,烙铁最高温度 260 度,焊接时间最长 10 秒 Lead wire should be soldered with 10S with the iron heated to a tip temperature 260°C (Max)	

## ※ 选型指南 Part Number Guide

CH	X32SB-12.000M	1	12	B1	-	N	T
CHXTAL	型号 Table1	频率 Frequency Range	振荡模式 1: Fund 3: 3RD 5: 5thovertone	负载电容(PF) Load Capacitance		附加加工 N: 普通 Normal C: 切脚 Lead Cutting G: 弯脚 Gull Wing J: 套管 Jacket I: 绝缘垫片 Insulator	包装方式 B: 散包 Bulk T: 编带 Tape
						温度特性 Table2	

## ※ Table1 型号/Type

A	B	C	D	E	F	G	H
X11SB	X21SB	X22SB	X32SB	X32GB	X53SB	X53SA	X53GA

## ※ Table2 温度特性及频差/Frequency stability at Temperature Range

温度特性及频差 Frequency stability @Temperature Range							
	Temp (°C)	-10~60	-20~70	-40~85	-40~105	-40~125	-55~125
Stability (ppm)		A	B	C	D	E	F
±10	1	*	*				
±20	2	*	*	*			
±30	3	*	*	*			
±50	5	*	*	*			